

DSC2G03

Silicon NPN epitaxial planar type

For high-frequency amplification

■ Features

- High forward current transfer ratio h_{FE} with excellent linearity
- High transition frequency f_T
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	30	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-base voltage (Collector open)	V_{EBO}	3	V
Collector current	I_C	50	mA
Collector power dissipation	P_C	200	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Package

- Code
Mini3-G3-B
- Pin Name
 1. Base
 2. Emitter
 3. Collector

■ Marking Symbol: C6

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 100 \mu\text{A}, I_E = 0$	30			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	3			V
Base-emitter voltage	V_{BE}	$V_{CE} = 10 \text{V}, I_C = 2 \text{mA}$		740		mV
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{V}, I_C = 2 \text{mA}$	25		250	—
Transition frequency ^{*1, 2}	f_T	$V_{CE} = 10 \text{V}, I_C = 15 \text{mA}$	800		1600	MHz
Reverse transfer capacitance (Common emitter)	C_{re}	$V_{CE} = 10 \text{V}, I_C = 1 \text{mA}, f = 10.7 \text{MHz}$		0.9		pF
Reverse transfer capacitance (Common base)	C_{rb}	$V_{CB} = 6 \text{V}, I_C = 0, f = 1 \text{MHz}$		0.7		pF
Power gain	PG	$V_{CE} = 10 \text{V}, I_C = 1 \text{mA}, f = 200 \text{MHz}$		20		dB

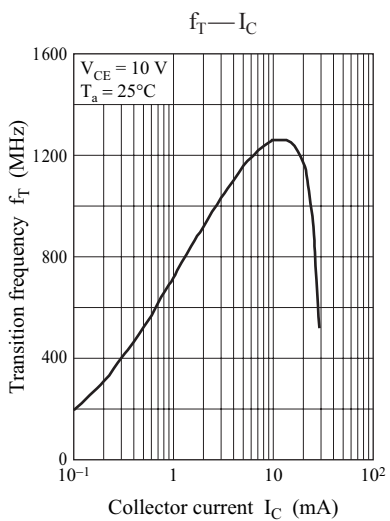
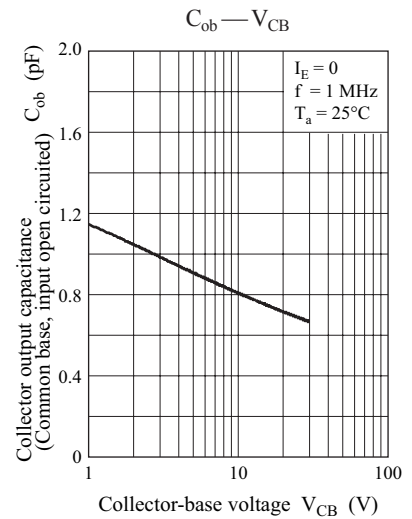
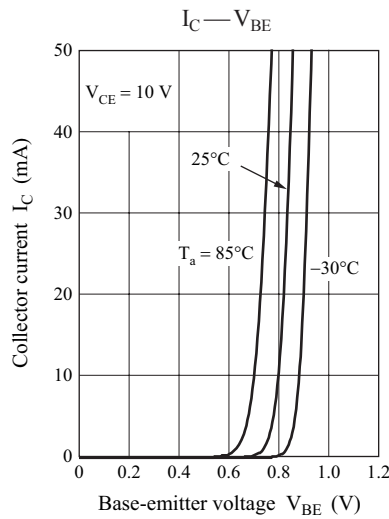
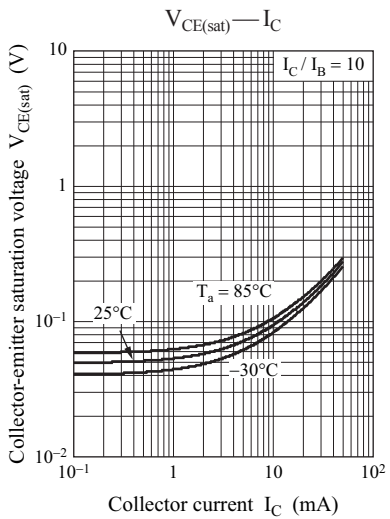
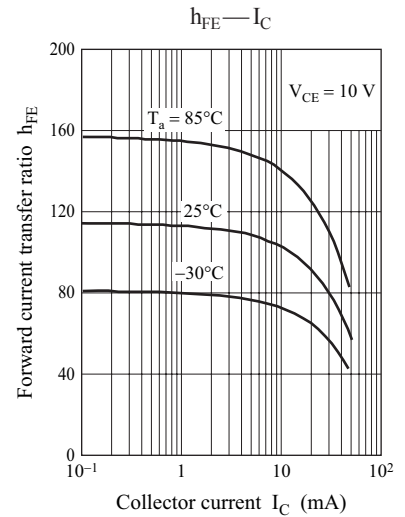
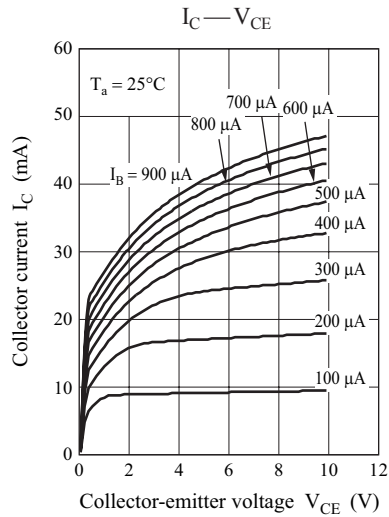
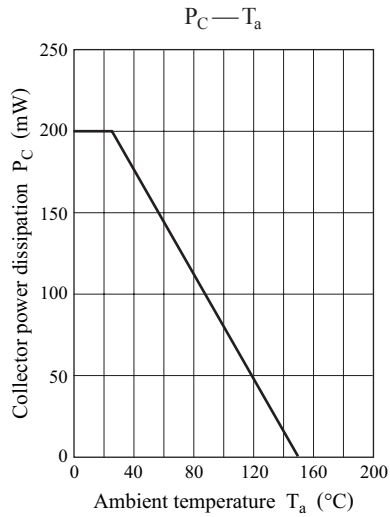
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

*2: Rank classification

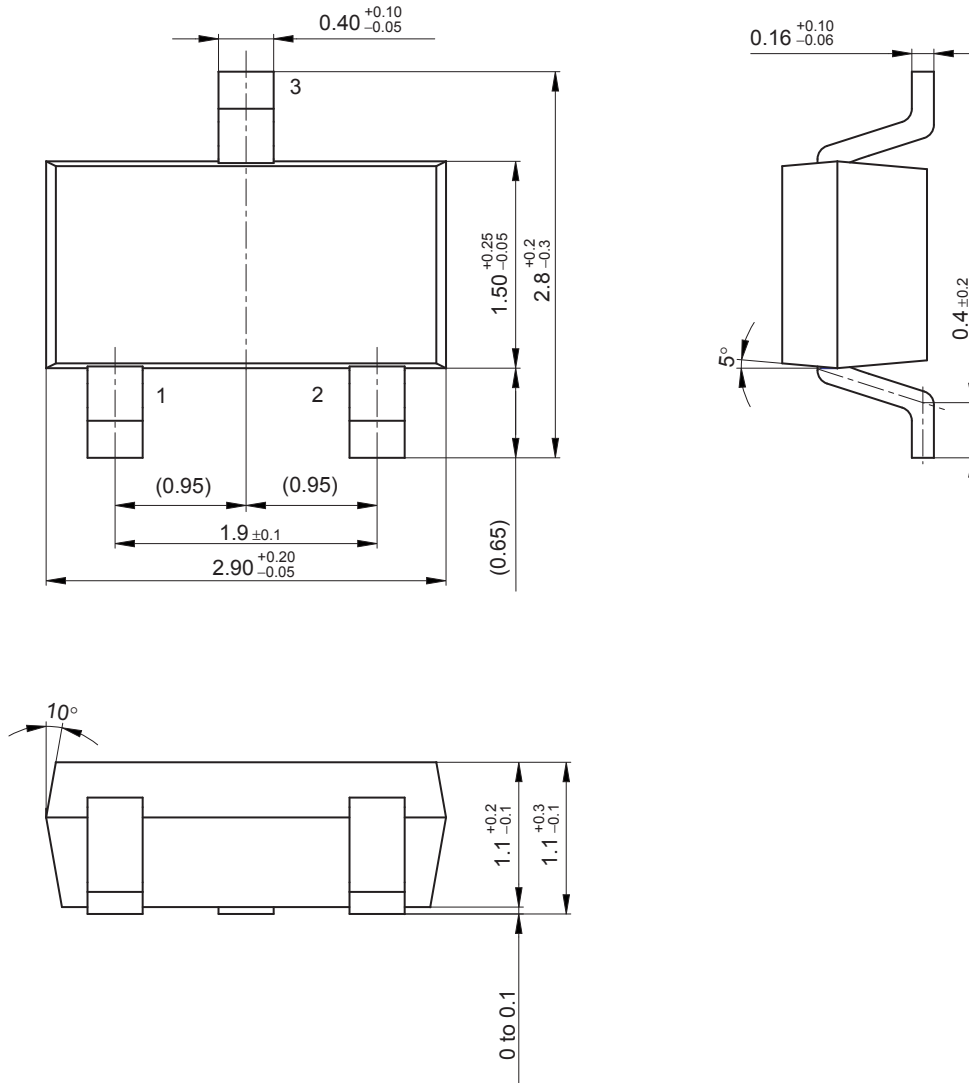
Code	T	S	0
Rank	T	S	No-rank
f_T	800 to 1400	1 000 to 1 600	800 to 1 600
Marking Symbol	C6T	C6S	C6

Product of no-rank is not classified and have no marking symbol for rank.



Mini3-G3-B

Unit: mm



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